contact Name  Title - Contact Phone - Contact*  Product-Env-Stewards Product-Enviro Compliance Authorized Representative*  Title - Representative Phone - Representative*  Z024-04-19 Email - Contact*  Product-Env-Stewards Product-Env-Stewards@onsemi.com Product-Env-Stewards@onsemi.com Phone - Representative*  Email - Representative*	IPC ASSOCIATION CONNECTIN	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company unique ID Unique ID Authority Description De	752-21.1						*					ials and Mf	fg Informat	ion	
Semilar   Contact Name   Title - Contact   Phone - Contact*   Phone - Contact*   Product-Env-Stewards @ onsemi.com	upplier Inforn	nation								,			<u> </u>		
Title - Contact Name Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Prod	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product-Env-Stewards Authorized Representative* Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product-Env-S	onsemi											2024-04-19			
Authorized Representative*  Title - Representative Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester It	Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  Manufacturing Process Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  Terminal Plating / Grid Array Material  Terminal Base Alloy  Manufacturing  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  Matte Tin (Sn) - annealed  CU Alloy  1  260  C  30  Seconds  3	Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
FAN23SV06PAMPX 6 A Buck Regulator 2024-04-19 PBB 83.149 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requesto	Requester Item Number Mfr Ite		Number	Mfr Item Name			Effective Date	Version	Manuf	Manufacturing Site		Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3		FAN23SV06PA		V06PAMPX	06PAMPX 6 A Buck Regulator			2024-04-19 PBB			8	33.149	mg	Each	
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3				Comminal Dago	Aller	CTD 020 MCI	Dating	Dools Drogo	as Dody Town	oroturo M	ov Time at Dook	Tommonoto	wa Numb	act of Deflow Cur	las
	5 -			•		. Kanng			ax 11me at Peak			ber of Reflow Cyc	ies		
omments	•	ın (Sii) - aimealed	C	U Alloy	1			200	<u> C</u>	30		second	18 3		
vel 1 - maximum time at peak temperature during soldering is 10-30 seconds		time at neak temperatur	no dunina sal	doring is 10.2	0 soconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applica										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.14	mg	Supplier	Silicon (Si)	7440-21-3		1.14	mg
Die Attach Solder	1.362	mg	Supplier	Silver (Ag)	7440-22-4		0.034	mg
			A	Lead (Pb)	7439-92-1	7a	1.2599	mg
			Supplier	Tin (Sn)	7440-31-5		0.0681	mg
Lead Frame	30.983	mg	Supplier	Silver (Ag)	7440-22-4		0.282	mg
			Supplier	Zinc (Zn)	7440-66-6		0.04	mg
			Supplier	Iron (Fe)	7439-89-6		0.744	mg
			Supplier	Copper (Cu)	7440-50-8		29.917	mg
Mold Compound-Black	46.6	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		4.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.466	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.008	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.932	mg
Plating	1.78	mg	Supplier	Tin (Sn)	7440-31-5		1.78	mg
Wire Bond - Au	0.684	mg	Supplier	Gold (Au)	7440-57-5		0.684	mg
Wire Bond - Cu	0.6	mg	Supplier	Palladium (Pd)	7440-05-3		0.012	mg
			Supplier	Copper (Cu)	7440-50-8		0.588	mg